

CERAMIC PACKAGES

Addison Engineering stocks over 3.5 million ceramic packages and in excess of one-million metal alloy lids. These include:

- Ceramic Dual-In-Line Frit Seal Packages (CerDIPs)
- Ceramic Dual-In-Line Metal Seal Packages or Sidebrazed (SBDIPs)
- Ceramic Leadless Chip carrier Packages (CLCCs)
- Ceramic Metal Seal Flatpack Packages (Flatpacks)
- Ceramic Pin Grid Array Packages (CPGA)
- Ceramic Quad Flatpack Packages (CQFP)
- Hermetic Metal Packages
- Metal Can Packages or Headers (Cans)

Our large inventory allows you to select from a variety of different configurations. The packages are Kyocera and NTK manufactured. The lids are gold plated and have gold-tin eutectic performs attached. We specialize in both small and large orders and can typically ship within 24 hours.

CERAMIC PACKAGE ASSEMBLY

Addison Engineering can also handle your assembly requirements. We provide fast turn assembly services, from precision wafer dicing, through die attach, wire bond, and seal plus test and burn-in. Our staff can free up your valuable engineering resources by taking your assembly from prototype through full production volumes.

